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Electronic Patent Application Submission

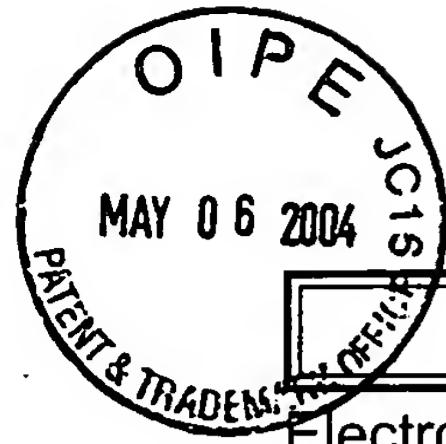
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EFS ID: 60527
Application ID: 10626150
Title of Invention: PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE
First Named Inventor: THOMAS GLENN
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-07-24
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Submission Type: Information Disclosure
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Confirmation number: 9302
Attorney Docket Number: AMKOR007C2



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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE	
<p>Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P. Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids3-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

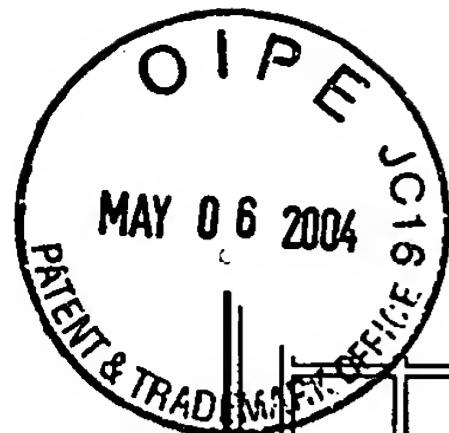


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND AND LEADFRAME FOR MAKING THE PACKAGE						
Application Number:	10/626150						
Confirmation Number:	9302						
First Named Applicant:	THOMAS GLENN						
Attorney Docket Number:	AMKOR007C2						
Art Unit:	2815						
Search string:	(5608265 or 5608267 or 5625222 or 5633528 or 5639990 or 5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5724233 or 5723899 or 5726493 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or 5877043 or 5886397).pn.						
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Signature

Examiner Name	Date